

A1
cont'd

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component and a second component includes the steps of
providing a sensor chip assembly as the first component, and
providing a mounting platform as the second component.

15. (Amended) The method of claim 11, wherein the step of providing a first component and a second component includes the steps of
providing a sensor chip assembly as the first component.

A2
16. (Amended) The method of claim 11, wherein the step of providing a first component and a second component includes the steps of
providing a sensor chip assembly as the first component, and
providing a mounting platform as the second component.
